

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 64-054749
 (43)Date of publication of application : 02.03.1989

(51)Int.Cl.

H01L 23/28
 H01L 21/60
 H01L 23/50

(21)Application number : 62-211993
 (22)Date of filing : 26.08.1987

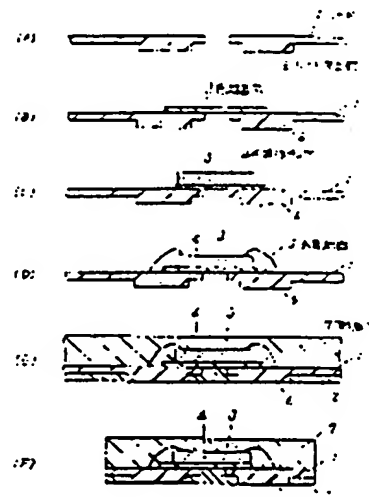
(71)Applicant : MATSUSHITA ELECTRIC IND CO LTD
 (72)Inventor : KITAHIRO ISAMU
 KONDO SHUJI
 KIKUCHI TATSUO
 TAKASE YOSHIHISA

(54) SEMICONDUCTOR DEVICE AND MANUFACTURE THEREOF

(57)Abstract:

PURPOSE: To obtain a highly accurate and highly reliable semiconductor device by placing a semiconductor chip through an insulating substrate on one group of highly accurate metal leads, connecting the leads to fine metal wirings, and transfer molding them.

CONSTITUTION: A thin resin plate 3 is attached to leads 1 having protrusions 6, and electrodes on a semiconductor chip 4 are connected to the leads 1 by fine metal wirings 5. Then, the leads except the protrusions 6 are sealed with resins 2, 7, shape and size are determined and cut. According to this structure, a small-sized and thin semiconductor device having high dimensional accuracy and reliability is obtained without complicated structure like a both-side substrate only by employing metal leads of special shape at part, and is preferably adapted for an IC.



LEGAL STATUS

[Date of request for examination]
 [Date of sending the examiner's decision of rejection]
 [Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]
 [Date of final disposal for application]
 [Patent number]
 [Date of registration]
 [Number of appeal against examiner's decision of rejection]
 [Date of requesting appeal against examiner's decision of rejection]
 [Date of extinction of right]

Copyright (C): 1998,2000 Japan Patent Office

BEST AVAILABLE COPY

図 2

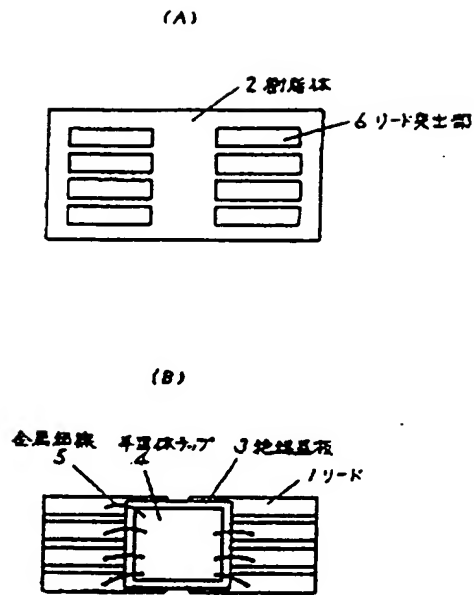


図 3

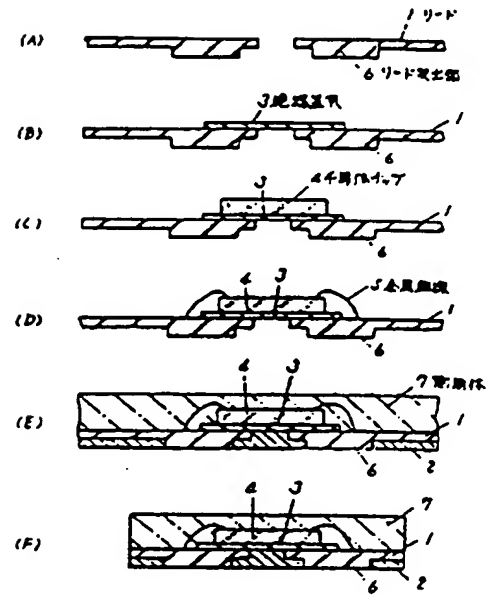


図 4

